

nd, respectively, to previously considered claims 10, 14, and 26 that the Examiner deemed patentable if rewritten in independent form. These claims, and the claims dependent from these claims, are submitted to be allowable.

The present invention provides materials that can be used, **universally**, by makers of printed circuit boards to provide embedded capacitor structures. In its simplest form, such materials comprise a two-layer laminate of a metal foil and a thin layer dielectric material. This is recited in independent Claim 29. To this can be added a second metal layer to form a three-layer laminate as recited in Claim 35. In the two-layer laminate a surface of the foil layer and a surface of the dielectric are exposed. In the three-layer laminate, a surface of each metal layer is exposed. Exposure of these surfaces are now recited in amended Claims 29 and 35. Support for the language "exposed surfaces" is found in the circuitization method described in reference to Figures 4A-4C.

Claims 29 and 35, as amended, are neither anticipated nor obvious from Laufer et al. (5,027,253). Laufer et al. describe a device that incorporates embedded capacitors, but in no way does it describe a material that can be universally used by printed circuit board manufacturers. Specifically, it describes neither a two-layer laminate having two exposed surfaces that can be universally used (circuitized to the requirements of the manufacturer), nor a three layer laminate that can be universally used.

In Laufer (See the flow chart of Fig. 1 and the Example), a metal foil is laminated to a PTFE support and this foil layer is **circuitized**. On this is deposited a dielectric layer, and then a second metal layer. The circuitization of the first metal layer is **specific to the device, but precludes its universal use**.

Accordingly, Claims 29 and 35, and the claims depending from each of these independent claims are believed to be allowable.

Newly submitted Claim 37 is directed to another laminate universally useful for forming printed circuit board. To a polymeric support is deposited a first metal layer, a dielectric layer, and a second dielectric layer having an exposed surface. The first metal layer is un-patterned (as opposed to the patterned first metal layer in Laufer et al.) and is releasable from the polymeric support sheet. After the second metal layer is patterned, it is embedded in support material, such

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as epoxy pre-preg. Then the polymeric support sheet is removed from the first metal layer, allowing the first metal layer to be patterned.

In view of the recitations that apply to the universal applicability of the Claim 37 structure and distinguish over Lauffer et al., Claim 37 and Claims 38 and 39, depending therefrom are believed to be allowable.

All of the claims are believed to be in condition for allowance. Favorable action is courteously requested.

Respectfully submitted,

S. Matthew Cairns, Ph.D.
Attorney for Applicant
Registration No. 42,378
Telephone No: (508) 229-7545
Facsimile No.: (508) 485-0363

c/o EDWARDS & ANGELL
Dike, Bronstein, Roberts & Cushman IP Group
130 Water Street
Boston, MA
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